

IN THE CLAIMS:

Please AMEND claims 23-26, as follows. For the Examiner's convenience, all claims currently pending in this application have been reproduced below:

1-22. (Canceled)

23. (Currently Amended) An exposure apparatus for exposing a wafer to ~~light~~ radiation via a mask, said apparatus comprising:

a process chamber in which the wafer is exposed to the ~~light~~ radiation;

a load-lock chamber including first and second gate valves, and connected to said process chamber via [[a]] said first gate valve;

a booth connected to said load-lock chamber via said second gate valve;

a transfer mechanism arranged in said booth and configured to transfer the wafer from another apparatus different from said exposure apparatus into said load-lock chamber through said booth;

~~a booth which is connected to said load-lock chamber via a gate valve and covers said transfer mechanism; and~~

a gas flow forming mechanism ~~which includes~~ including a filter and ~~causes~~ configured to cause gas through said filter to flow through said booth.

24. (Currently Amended) An apparatus according to claim 23, wherein said gas flow forming mechanism ~~comprises~~ includes a circulation unit configured to exhaust gas from said booth and to return the exhausted gas to said booth through said filter.

25. (Currently Amended) An apparatus according to claim 23, wherein said gas flow forming mechanism ~~comprises~~ includes a fan unit configured to supply gas to said booth through said filter.

26. (Currently Amended) An apparatus according to claim 23, wherein said gas flow forming mechanism is ~~arranged~~ configured to form a laminar flow of the gas in said booth.

27. (Previously Presented) An apparatus according to claim 23, wherein the other apparatus is a coater/developer.